

Features

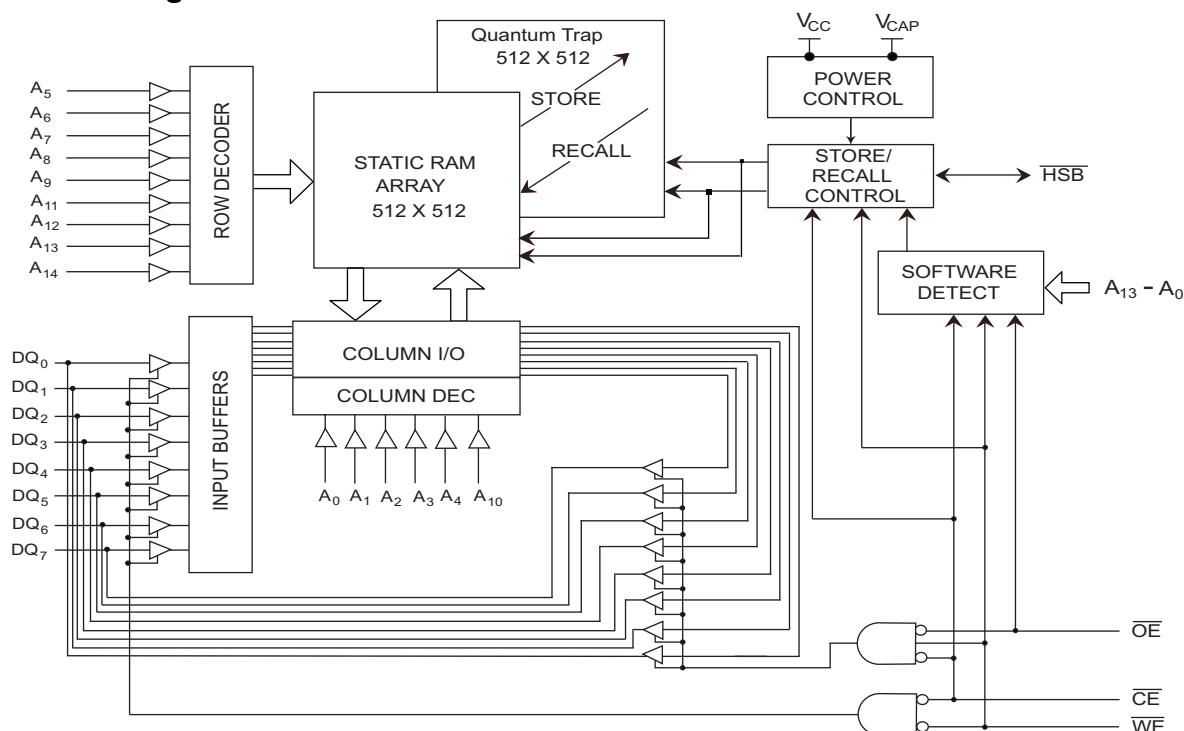
- 25 ns and 45 ns access times
- Internally organized as 32 K × 8 (CY14B256LA)
- Hands off automatic STORE on power-down with only a small capacitor
- STORE to QuantumTrap nonvolatile elements initiated by software, device pin, or AutoStore on power-down
- RECALL to SRAM initiated by software or power-up
- Infinite read, write, and recall cycles
- 1 million STORE cycles to QuantumTrap
- 20-year data retention
- Single 3 V +20% to -10% operation
- Industrial temperature
- 44-pin thin small outline package (TSOP) Type II, 48-pin shrunk small outline package (SSOP), and 32-pin small-outline integrated circuit (SOIC) packages
- Pb-free and restriction of hazardous substances (RoHS) compliance

Functional Description

The Cypress CY14B256LA is a fast static RAM, with a nonvolatile element in each memory cell. The memory is organized as 32 K bytes of 8 bits each. The embedded nonvolatile elements incorporate QuantumTrap technology, producing the world's most reliable nonvolatile memory. The SRAM provides infinite read and write cycles, while independent nonvolatile data resides in the highly reliable QuantumTrap cell. Data transfers from the SRAM to the nonvolatile elements (the STORE operation) takes place automatically at power-down. On power-up, data is restored to the SRAM (the RECALL operation) from the nonvolatile memory. Both the STORE and RECALL operations are also available under software control.

For a complete list of related documentation, click [here](#).

Logic Block Diagram



Contents

| | | | |
|--|-----------|--|-----------|
| Pinouts | 3 | Switching Waveforms | 11 |
| Pin Definitions | 4 | AutoStore/Power-Up RECALL | 13 |
| Device Operation | 5 | Switching Waveforms | 13 |
| SRAM Read | 5 | Software Controlled STORE/RECALL Cycle | 14 |
| SRAM Write | 5 | Switching Waveforms | 14 |
| AutoStore Operation | 5 | Hardware STORE Cycle | 15 |
| Hardware STORE Operation | 5 | Switching Waveforms | 15 |
| Hardware RECALL (Power-Up) | 6 | Truth Table For SRAM Operations | 16 |
| Software STORE | 6 | Ordering Information | 16 |
| Software RECALL | 6 | Ordering Code Definitions | 16 |
| Preventing AutoStore | 7 | Package Diagrams | 17 |
| Data Protection | 7 | Acronyms | 20 |
| Maximum Ratings | 8 | Document Conventions | 20 |
| Operating Range | 8 | Units of Measure | 20 |
| DC Electrical Characteristics | 8 | Document History Page | 21 |
| Data Retention and Endurance | 9 | Sales, Solutions, and Legal Information | 22 |
| Capacitance | 9 | Worldwide Sales and Design Support | 22 |
| Thermal Resistance | 9 | Products | 22 |
| AC Test Loads | 10 | PSoC® Solutions | 22 |
| AC Test Conditions | 10 | Cypress Developer Community | 22 |
| AC Switching Characteristics | 11 | Technical Support | 22 |

Pinouts

Figure 1. 44-pin TSOP II / 48-pin SSOP pinout

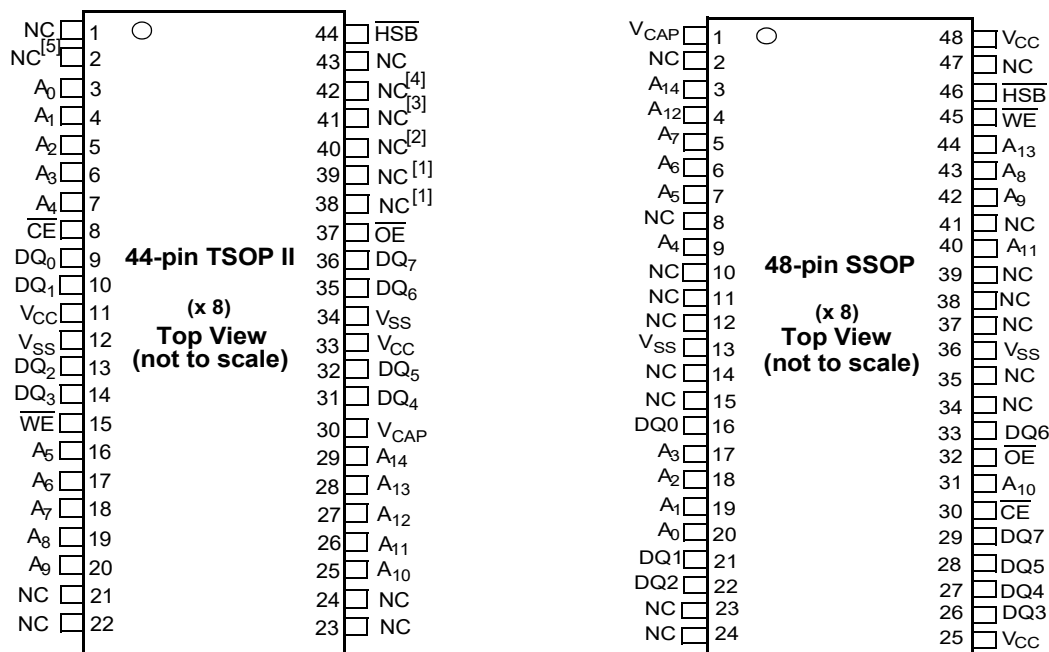
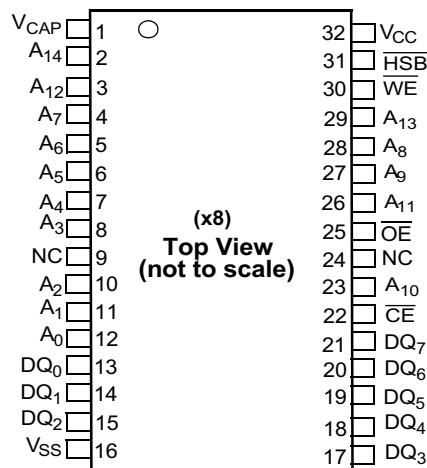


Figure 2. 32-pin SOIC pinout



Notes

1. Address expansion for 1-Mbit. NC pin not connected to die.
2. Address expansion for 2-Mbit. NC pin not connected to die.
3. Address expansion for 4-Mbit. NC pin not connected to die.
4. Address expansion for 8-Mbit. NC pin not connected to die.
5. Address expansion for 16-Mbit. NC pin not connected to die.

Pin Definitions

| Pin Name | I/O Type | Description |
|----------------------------------|--------------|---|
| A ₀ –A ₁₄ | Input | Address inputs. Used to select one of the 32,768 bytes of the nvSRAM. |
| DQ ₀ –DQ ₇ | Input/Output | Bidirectional data I/O lines. Used as input or output lines depending on operation. |
| $\overline{\text{WE}}$ | Input | Write enable input, active LOW. When the chip is enabled and WE is LOW, data on the I/O pins is written to the specific address location. |
| $\overline{\text{CE}}$ | Input | Chip enable input, active LOW. When LOW, selects the chip. When HIGH, deselects the chip. |
| $\overline{\text{OE}}$ | Input | Output enable, active LOW. The active LOW $\overline{\text{OE}}$ input enables the data output buffers during read cycles. I/O pins are tristated on deasserting $\overline{\text{OE}}$ HIGH. |
| V _{SS} | Ground | Ground for the device. Must be connected to the ground of the system. |
| V _{CC} | Power supply | Power supply inputs to the device. 3.0 V +20%, –10% |
| $\overline{\text{HSB}}$ | Input/Output | Hardware STORE busy ($\overline{\text{HSB}}$). When LOW this output indicates that a Hardware STORE is in progress. When pulled LOW external to the chip it initiates a nonvolatile STORE operation. After each Hardware and Software STORE operation $\overline{\text{HSB}}$ is driven HIGH for a short time (t _{HHHD}) with standard output high current and then a weak internal pull-up resistor keeps this pin HIGH (External pull-up resistor connection optional). |
| V _{CAP} | Power supply | AutoStore capacitor. Supplies power to the nvSRAM during power loss to store data from SRAM to nonvolatile elements. |
| NC | No connect | No connect. This pin is not connected to the die. |

Device Operation

The CY14B256LA nvSRAM is made up of two functional components paired in the same physical cell. They are an SRAM memory cell and a nonvolatile QuantumTrap cell. The SRAM memory cell operates as a standard fast static RAM. Data in the SRAM is transferred to the nonvolatile cell (the STORE operation), or from the nonvolatile cell to the SRAM (the RECALL operation). Using this unique architecture, all cells are stored and recalled in parallel. During the STORE and RECALL operations, SRAM read and write operations are inhibited. The CY14B256LA supports infinite reads and writes similar to a typical SRAM. In addition, it provides infinite RECALL operations from the nonvolatile cells and up to 1 million STORE operations. Refer to the [Truth Table For SRAM Operations on page 16](#) for a complete description of read and write modes.

SRAM Read

The CY14B256LA performs a read cycle when \overline{CE} and \overline{OE} are LOW and \overline{WE} and HSB are HIGH. The address specified on pins A_{0-14} determines which of the 32,768 data bytes each are accessed. When the read is initiated by an address transition, the outputs are valid after a delay of t_{AA} (read cycle 1). If the read is initiated by \overline{CE} or \overline{OE} , the outputs are valid at t_{ACE} or at t_{DOE} , whichever is later (read cycle 2). The data output repeatedly responds to address changes within the t_{AA} access time without the need for transitions on any control input pins. This remains valid until another address change or until \overline{CE} or \overline{OE} is brought HIGH, or \overline{WE} or HSB is brought LOW.

SRAM Write

A write cycle is performed when \overline{CE} and \overline{WE} are LOW and HSB is HIGH. The address inputs must be stable before entering the write cycle and must remain stable until \overline{CE} or \overline{WE} goes HIGH at the end of the cycle. The data on the common I/O pins DQ_{0-7} are written into the memory if the data is valid t_{SD} before the end of a \overline{WE} -controlled write or before the end of a \overline{CE} -controlled write. Keep \overline{OE} HIGH during the entire write cycle to avoid data bus contention on common I/O lines. If \overline{OE} is left LOW, internal circuitry turns off the output buffers t_{HZWE} after \overline{WE} goes LOW.

AutoStore Operation

The CY14B256LA stores data to the nvSRAM using one of the following three storage operations: Hardware STORE activated by HSB; Software STORE activated by an address sequence; AutoStore on device power-down. The AutoStore operation is a unique feature of QuantumTrap technology and is enabled by default on the CY14B256LA.

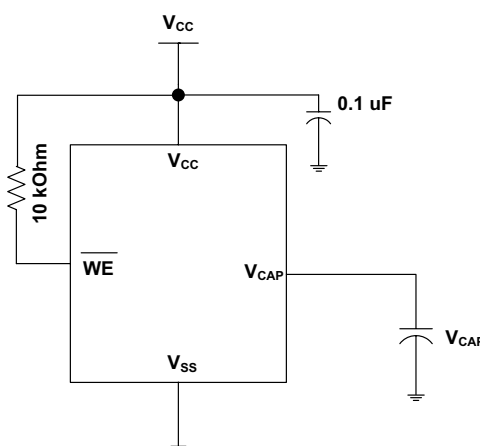
During a normal operation, the device draws current from V_{CC} to charge a capacitor connected to the V_{CAP} pin. This stored charge is used by the chip to perform a single STORE operation. If the voltage on the V_{CC} pin drops below V_{SWITCH} , the part automatically disconnects the V_{CAP} pin from V_{CC} . A STORE operation is initiated with power provided by the V_{CAP} capacitor.

Note If the capacitor is not connected to V_{CAP} pin, AutoStore must be disabled using the soft sequence specified in [Preventing AutoStore on page 7](#). In case AutoStore is enabled without a capacitor on V_{CAP} pin, the device attempts an AutoStore operation without sufficient charge to complete the Store. This will corrupt the data stored in nvSRAM.

Figure 3 shows the proper connection of the storage capacitor (V_{CAP}) for automatic STORE operation. Refer to [DC Electrical Characteristics on page 8](#) for the size of V_{CAP} . The voltage on the V_{CAP} pin is driven to V_{CC} by a regulator on the chip. Place a pull-up on \overline{WE} to hold it inactive during power-up. This pull-up is only effective if the \overline{WE} signal is tristate during power-up. Many MPUs tristate their controls on power-up. This must be verified when using the pull-up. When the nvSRAM comes out of power-on-recall, the MPU must be active or the \overline{WE} held inactive until the MPU comes out of reset.

To reduce unnecessary nonvolatile stores, AutoStore and Hardware STORE operations are ignored unless at least one write operation has taken place since the most recent STORE or RECALL cycle. Software-initiated STORE cycles are performed regardless of whether a write operation has taken place. The HSB signal is monitored by the system to detect if an AutoStore cycle is in progress.

Figure 3. AutoStore Mode



Hardware STORE Operation

The CY14B256LA provides the HSB pin to control and acknowledge the STORE operations. Use the HSB pin to request a Hardware STORE cycle. When the HSB pin is driven LOW, the CY14B256LA conditionally initiates a STORE operation after t_{DELAY} . An actual STORE cycle only begins if a write to the SRAM has taken place since the last STORE or RECALL cycle. The HSB pin also acts as an open drain driver (internal 100 kΩ weak pull-up resistor) that is internally driven LOW to indicate a busy condition when the STORE (initiated by any means) is in progress.

Note After each Hardware and Software STORE operation HSB is driven HIGH for a short time (t_{HHHD}) with standard output high current and then remains HIGH by internal 100 kΩ pull-up resistor.

SRAM write operations that are in progress when HSB is driven LOW by any means are given time (t_{DELAY}) to complete before the STORE operation is initiated. However, any SRAM write cycles requested after HSB goes LOW are inhibited until HSB returns HIGH. In case the write latch is not set, HSB is not driven LOW by the CY14B256LA. But any SRAM read and write cycles are inhibited until HSB is returned HIGH by MPU or other external source.

During any STORE operation, regardless of how it is initiated, the CY14B256LA continues to drive the HSB pin LOW, releasing it only when the STORE is complete. Upon completion of the STORE operation, the nvSRAM memory access is inhibited for t_{LZHSB} time after HSB pin returns HIGH. Leave the HSB unconnected if it is not used.

Hardware RECALL (Power-Up)

During power-up or after any low-power condition ($V_{CC} < V_{SWITCH}$), an internal RECALL request is latched. When V_{CC} again exceeds the sense voltage of V_{SWITCH} , a RECALL cycle is automatically initiated and takes $t_{HRECALL}$ to complete. During this time, HSB is driven low by the HSB driver.

Software STORE

Data is transferred from SRAM to the nonvolatile memory by a software address sequence. The CY14B256LA Software STORE cycle is initiated by executing sequential \overline{CE} or \overline{OE} controlled read cycles from six specific address locations in exact order. During the STORE cycle an erase of the previous nonvolatile data is first performed, followed by a program of the nonvolatile elements. After a STORE cycle is initiated, further input and output are disabled until the cycle is completed.

Because a sequence of READs from specific addresses is used for STORE initiation, it is important that no other read or write accesses intervene in the sequence, or the sequence is aborted and no STORE or RECALL takes place.

To initiate the Software STORE cycle, the following read sequence must be performed:

1. Read address 0x0E38 valid READ
2. Read address 0x31C7 valid READ
3. Read address 0x03E0 valid READ
4. Read address 0x3C1F valid READ
5. Read address 0x303F valid READ
6. Read address 0x0FC0 initiate STORE cycle

The software sequence may be clocked with \overline{CE} controlled reads or \overline{OE} controlled reads, with \overline{WE} kept HIGH for all the six READ sequences. After the sixth address in the sequence is entered, the STORE cycle commences and the chip is disabled. HSB is driven LOW. After the t_{STORE} cycle time is fulfilled, the SRAM is activated again for the read and write operation.

Software RECALL

Data is transferred from nonvolatile memory to the SRAM by a software address sequence. A Software RECALL cycle is initiated with a sequence of read operations in a manner similar to the Software STORE initiation. To initiate the RECALL cycle, the following sequence of \overline{CE} or \overline{OE} controlled read operations must be performed:

1. Read address 0x0E38 valid READ
2. Read address 0x31C7 valid READ
3. Read address 0x03E0 valid READ
4. Read address 0x3C1F valid READ
5. Read address 0x303F valid READ
6. Read address 0x0C63 initiate RECALL cycle

Internally, RECALL is a two step procedure. First, the SRAM data is cleared. Next, the nonvolatile information is transferred into the SRAM cells. After the t_{RECALL} cycle time, the SRAM is again ready for read and write operations. The RECALL operation does not alter the data in the nonvolatile elements.

Table 1. Mode Selection

| \overline{CE} | \overline{WE} | \overline{OE} | $A_{14}-A_0^{[6]}$ | Mode | I/O | Power |
|-----------------|-----------------|-----------------|--|---|--|-----------------------|
| H | X | X | X | Not selected | Output high Z | Standby |
| L | H | L | X | Read SRAM | Output data | Active |
| L | L | X | X | Write SRAM | Input data | Active |
| L | H | L | 0x0E38 0x31C7 0x03E0 0x3C1F 0x303F 0x0B45 | Read SRAM Read SRAM Read SRAM Read SRAM Read SRAM AutoStore Disable | Output data Output data Output data Output data Output data Output data | Active ^[7] |

Notes

6. While there are 15 address lines on the CY14B256LA, only the lower 14 are used to control software modes.
7. The six consecutive address locations must be in the order listed. \overline{WE} must be HIGH during all six cycles to enable a nonvolatile cycle.

Table 1. Mode Selection (continued)

| \overline{CE} | \overline{WE} | \overline{OE} | $A_{14}-A_0^{[6]}$ | Mode | I/O | Power |
|-----------------|-----------------|-----------------|--|--|--|------------------------|
| L | H | L | 0x0E38 0x31C7 0x03E0 0x3C1F 0x303F 0x0B46 | Read SRAM Read SRAM Read SRAM Read SRAM Read SRAM AutoStore Enable | Output data Output data Output data Output data Output data Output data | Active ^[8] |
| L | H | L | 0x0E38 0x31C7 0x03E0 0x3C1F 0x303F 0x0FC0 | Read SRAM Read SRAM Read SRAM Read SRAM Read SRAM Nonvolatile STORE | Output data Output data Output data Output data Output data Output high Z | Active $I_{CC2}^{[8]}$ |
| L | H | L | 0x0E38 0x31C7 0x03E0 0x3C1F 0x303F 0x0C63 | Read SRAM Read SRAM Read SRAM Read SRAM Read SRAM Nonvolatile Recall | Output data Output data Output data Output data Output data Output high Z | Active ^[8] |

Preventing AutoStore

The AutoStore function is disabled by initiating an AutoStore disable sequence. A sequence of read operations is performed in a manner similar to the Software STORE initiation. To initiate the AutoStore disable sequence, the following sequence of \overline{CE} or \overline{OE} controlled read operations must be performed:

1. Read address 0x0E38 valid READ
2. Read address 0x31C7 valid READ
3. Read address 0x03E0 valid READ
4. Read address 0x3C1F valid READ
5. Read address 0x303F valid READ
6. Read address 0x0B45 AutoStore disable

The AutoStore is reenabled by initiating an AutoStore enable sequence. A sequence of read operations is performed in a manner similar to the Software RECALL initiation. To initiate the

AutoStore enable sequence, the following sequence of \overline{CE} or \overline{OE} controlled read operations must be performed:

1. Read address 0x0E38 valid READ
2. Read address 0x31C7 valid READ
3. Read address 0x03E0 valid READ
4. Read address 0x3C1F valid READ
5. Read address 0x303F valid READ
6. Read address 0x0B46 AutoStore enable

If the AutoStore function is disabled or reenabled, a manual STORE operation (Hardware or Software) must be issued to save the AutoStore state through subsequent power-down cycles. The part comes from the factory with AutoStore enabled and 0x00 written in all cells.

Data Protection

The CY14B256LA protects data from corruption during low voltage conditions by inhibiting all externally initiated STORE and write operations. The low voltage condition is detected when V_{CC} is less than V_{SWITCH} . If the CY14B256LA is in a write mode (both \overline{CE} and \overline{WE} are LOW) at power-up, after a RECALL or STORE, the write is inhibited until the SRAM is enabled after t_{LZHSB} (HSB to output active). This protects against inadvertent writes during power-up or brown out conditions.

Note

8. The six consecutive address locations must be in the order listed. \overline{WE} must be HIGH during all six cycles to enable a nonvolatile cycle.

Maximum Ratings

Exceeding maximum ratings may impair the useful life of the device. These user guidelines are not tested.

Storage temperature -65 °C to +150 °C

Maximum accumulated storage time:

At 150 °C ambient temperature 1000 h

At 85 °C ambient temperature 20 years

Maximum junction temperature 150 °C

Supply voltage on V_{CC} relative to V_{SS} -0.5 V to 4.1 V

Voltage applied to outputs

in high Z state -0.5 V to $V_{CC} + 0.5$ V

Input voltage -0.5 V to $V_{CC} + 0.5$ V

Transient voltage (< 20 ns) on

any pin to ground potential -2.0 V to $V_{CC} + 2.0$ V

Package power dissipation

capability ($T_A = 25$ °C) 1.0 W

Surface mount Pb soldering

temperature (3 seconds) +260 °C

DC output current (1 output at a time, 1s duration) 15 mA

Static discharge voltage

(per MIL-STD-883, Method 3015) > 2001 V

Latch-up current > 200 mA

Operating Range

| Range | Ambient Temperature | V_{CC} |
|------------|---------------------|----------------|
| Industrial | -40 °C to +85 °C | 2.7 V to 3.6 V |

DC Electrical Characteristics

Over the [Operating Range](#)

| Parameter | Description | Test Conditions | Min | Typ ^[9] | Max | Unit |
|-----------------|---|---|----------------|--------------------|----------------|----------|
| V_{CC} | Power supply | | 2.7 | 3.0 | 3.6 | V |
| I_{CC1} | Average V_{CC} current | $t_{RC} = 25$ ns $t_{RC} = 45$ ns Values obtained without output loads ($I_{OUT} = 0$ mA) | — | — | 70 52 | mA mA |
| I_{CC2} | Average V_{CC} current during STORE | All inputs don't care, $V_{CC} = \text{Max}$ Average current for duration t_{STORE} | — | — | 10 | mA |
| I_{CC3} | Average V_{CC} current at $t_{RC} = 200$ ns, $V_{CC(Typ)}$, 25 °C | All inputs cycling at CMOS levels. Values obtained without output loads ($I_{OUT} = 0$ mA). | — | 35 | — | mA |
| I_{CC4} | Average V_{CAP} current during AutoStore cycle | All inputs don't Care. Average current for duration t_{STORE} | — | — | 5 | mA |
| I_{SB} | V_{CC} standby current | $\overline{CE} \geq (V_{CC} - 0.2$ V). $V_{IN} \leq 0.2$ V or $\geq (V_{CC} - 0.2$ V). Standby current level after nonvolatile cycle is complete. Inputs are static. $f = 0$ MHz. | — | — | 5 | mA |
| $I_{IX}^{[10]}$ | Input leakage current (except HSB) | $V_{CC} = \text{Max}$, $V_{SS} \leq V_{IN} \leq V_{CC}$ | -1 | — | +1 | μA |
| | Input leakage current (for HSB) | $V_{CC} = \text{Max}$, $V_{SS} \leq V_{IN} \leq V_{CC}$ | -100 | — | +1 | μA |
| I_{OZ} | Off-state output leakage current | $V_{CC} = \text{Max}$, $V_{SS} \leq V_{OUT} \leq V_{CC}$, \overline{CE} or $\overline{OE} \geq V_{IH}$ or $\overline{WE} \leq V_{IL}$ | -1 | — | +1 | μA |
| V_{IH} | Input HIGH voltage | | 2.0 | — | $V_{CC} + 0.5$ | V |
| V_{IL} | Input LOW voltage | | $V_{SS} - 0.5$ | — | 0.8 | V |
| V_{OH} | Output HIGH voltage | $I_{OUT} = -2$ mA | 2.4 | — | | V |
| V_{OL} | Output LOW voltage | $I_{OUT} = 4$ mA | — | — | 0.4 | V |

Notes

9. Typical values are at 25 °C, $V_{CC} = V_{CC(Typ)}$. Not 100% tested.

10. The HSB pin has $I_{OUT} = -2$ μA for V_{OH} of 2.4 V when both active high and low drivers are disabled. When they are enabled standard V_{OH} and V_{OL} are valid. This parameter is characterized but not tested.

DC Electrical Characteristics (continued)

Over the [Operating Range](#)

| Parameter | Description | Test Conditions | Min | Typ ^[9] | Max | Unit |
|-----------------------|---|------------------------------------|-----|--------------------|----------|---------|
| $V_{CAP}^{[11]}$ | Storage capacitor | Between V_{CAP} pin and V_{SS} | 61 | 68 | 180 | μF |
| $V_{VCAP}^{[12, 13]}$ | Maximum voltage driven on V_{CAP} pin by the device | $V_{CC} = \text{Max}$ | – | – | V_{CC} | V |

Data Retention and Endurance

Over the [Operating Range](#)

| Parameter | Description | Min | Unit |
|-----------|------------------------------|-------|-------|
| $DATA_R$ | Data retention | 20 | Years |
| NV_C | Nonvolatile STORE operations | 1,000 | K |

Capacitance

| Parameter ^[13] | Description | Test Conditions | Max | Unit |
|---------------------------|---------------------------------|---|-----|------|
| C_{IN} | Input capacitance (except HSB) | $T_A = 25^\circ C, f = 1 \text{ MHz}, V_{CC} = V_{CC(Typ)}$ | 7 | pF |
| | Input capacitance (for HSB) | | 8 | pF |
| C_{OUT} | Output capacitance (except HSB) | | 7 | pF |
| | Output capacitance (for HSB) | | 8 | pF |

Thermal Resistance

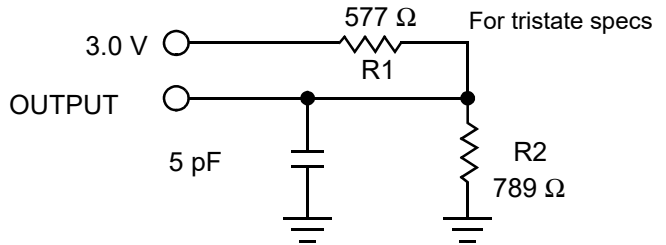
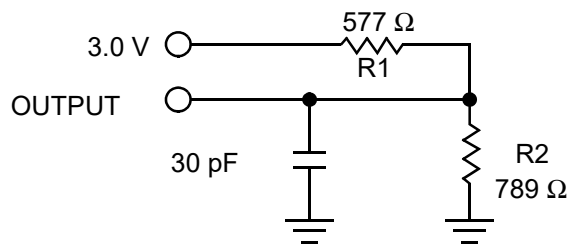
| Parameter ^[13] | Description | Test Conditions | 48-pin SSOP | 44-pin TSOP II | 32-pin SOIC | Unit |
|---------------------------|--|---|-------------|----------------|-------------|--------------|
| Θ_{JA} | Thermal resistance (Junction to ambient) | Test conditions follow standard test methods and procedures for measuring thermal impedance, in accordance with EIA/JESD51. | 37.47 | 41.74 | 41.55 | $^\circ C/W$ |
| Θ_{JC} | Thermal resistance (Junction to case) | | 24.71 | 11.9 | 24.43 | $^\circ C/W$ |

Notes

- Min V_{CAP} value guarantees that there is a sufficient charge available to complete a successful AutoStore operation. Max V_{CAP} value guarantees that the capacitor on V_{CAP} is charged to a minimum voltage during a Power-Up RECALL cycle so that an immediate power-down cycle can complete a successful AutoStore. Therefore it is always recommended to use a capacitor within the specified min and max limits. Refer application note [AN43593](#) for more details on V_{CAP} options.
- Maximum voltage on V_{CAP} pin (V_{VCAP}) is provided for guidance when choosing the V_{CAP} capacitor. The voltage rating of the V_{CAP} capacitor across the operating temperature range should be higher than the V_{VCAP} voltage.
- These parameters are guaranteed by design and are not tested.

AC Test Loads

Figure 4. AC Test Loads



AC Test Conditions

Input Pulse Levels 0 V to 3 V
 Input Rise and Fall Times (10%–90%) ≤ 3 ns
 Input and Output Timing Reference Levels 1.5 V

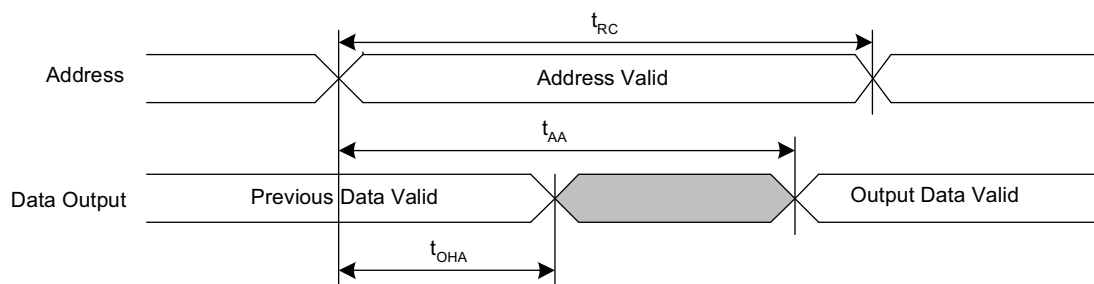
AC Switching Characteristics

Over the [Operating Range](#)

| Parameters ^[14] | | Description | 25 ns | | 45 ns | | Unit |
|---|------------------|-----------------------------------|-------|-----|-------|-----|------|
| Cypress Parameters | Alt Parameters | | Min | Max | Min | Max | |
| SRAM Read Cycle | | | | | | | |
| t _{ACE} | t _{ACS} | Chip enable access time | – | 25 | – | 45 | ns |
| t _{RC} ^[15] | t _{RC} | Read cycle time | 25 | – | 45 | – | ns |
| t _{AA} ^[16] | t _{AA} | Address access time | – | 25 | – | 45 | ns |
| t _{DOE} | t _{OE} | Output enable to data valid | – | 12 | – | 20 | ns |
| t _{OHA} ^[16] | t _{OH} | Output hold after address change | 3 | – | 3 | – | ns |
| t _{LZCE} ^[17, 18] | t _{LZ} | Chip enable to output active | 3 | – | 3 | – | ns |
| t _{HZCE} ^[17, 18] | t _{HZ} | Chip disable to output inactive | – | 10 | – | 15 | ns |
| t _{LZOE} ^[17, 18] | t _{OLZ} | Output enable to output active | 0 | – | 0 | – | ns |
| t _{HZOE} ^[17, 18] | t _{OHZ} | Output disable to output inactive | – | 10 | – | 15 | ns |
| t _{PU} ^[17] | t _{PA} | Chip enable to power active | 0 | – | 0 | – | ns |
| t _{PD} ^[17] | t _{PS} | Chip disable to power standby | – | 25 | – | 45 | ns |
| SRAM Write Cycle | | | | | | | |
| t _{WC} | t _{WC} | Write cycle time | 25 | – | 45 | – | ns |
| t _{PWE} | t _{WP} | Write pulse width | 20 | – | 30 | – | ns |
| t _{SCE} | t _{CW} | Chip enable to end of write | 20 | – | 30 | – | ns |
| t _{SD} | t _{DW} | Data setup to end of write | 10 | – | 15 | – | ns |
| t _{HD} | t _{DH} | Data hold after end of write | 0 | – | 0 | – | ns |
| t _{AW} | t _{AW} | Address setup to end of write | 20 | – | 30 | – | ns |
| t _{SA} | t _{AS} | Address setup to start of write | 0 | – | 0 | – | ns |
| t _{HA} | t _{WR} | Address hold after end of write | 0 | – | 0 | – | ns |
| t _{HZWE} ^[17, 18, 19] | t _{WZ} | Write enable to output disable | – | 10 | – | 15 | ns |
| t _{LOW} ^[17, 18] | t _{OW} | Output active after end of write | 3 | – | 3 | – | ns |

Switching Waveforms

Figure 5. SRAM Read Cycle #1 (Address Controlled) ^[15, 16, 20]



Notes

14. Test conditions assume signal transition time of 3 ns or less, timing reference levels of $V_{CC}/2$, input pulse levels of 0 to $V_{CC(typ)}$, and output loading of the specified I_{OL}/I_{OH} and load capacitance shown in [Figure 4](#).
15. WE must be HIGH during SRAM read cycles.
16. Device is continuously selected with CE and OE LOW.
17. These parameters are guaranteed by design and are not tested.
18. Measured ± 200 mV from steady state output voltage.
19. If WE is low when CE goes low, the outputs remain in the high impedance state.
20. HSB must remain HIGH during READ and WRITE cycles.

Switching Waveforms (continued)

Figure 6. SRAM Read Cycle #2 ($\overline{\text{CE}}$ and $\overline{\text{OE}}$ Controlled) [21, 22]

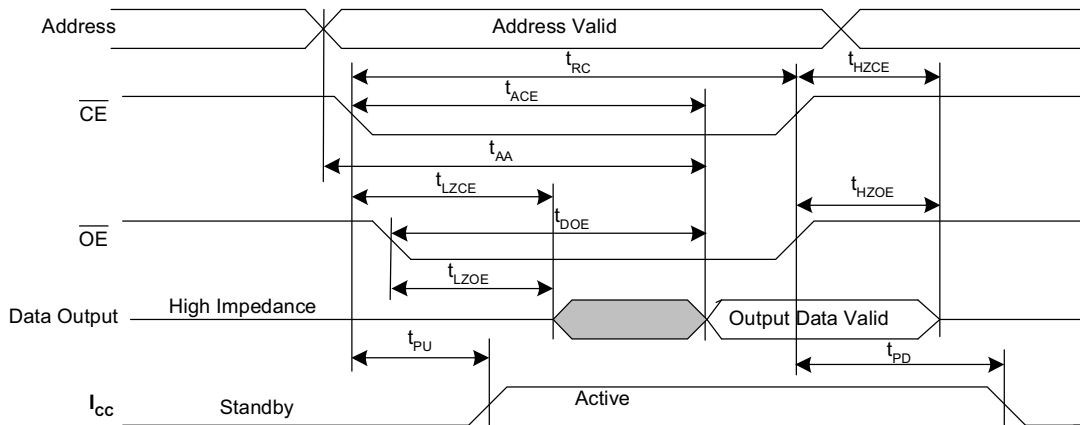


Figure 7. SRAM Write Cycle #1 ($\overline{\text{WE}}$ Controlled) [22, 23, 24]

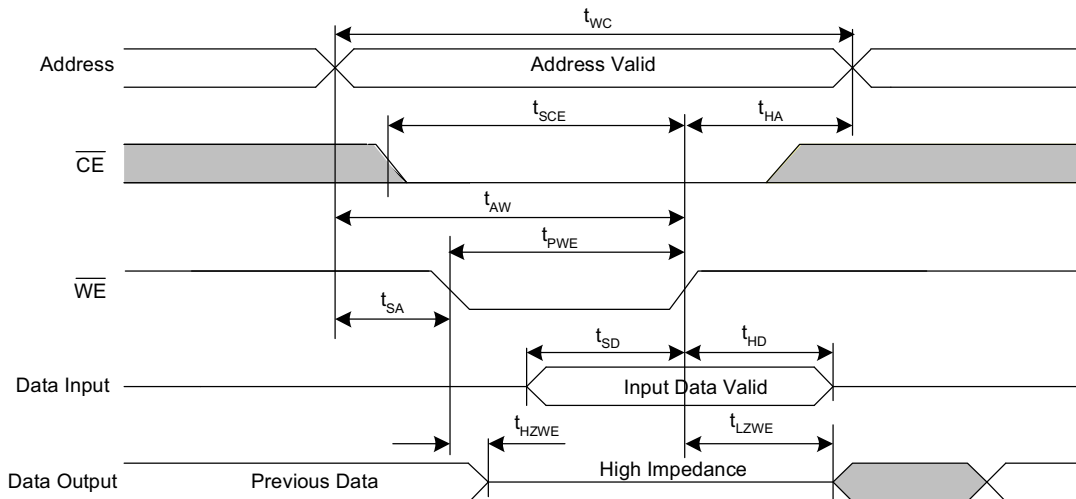
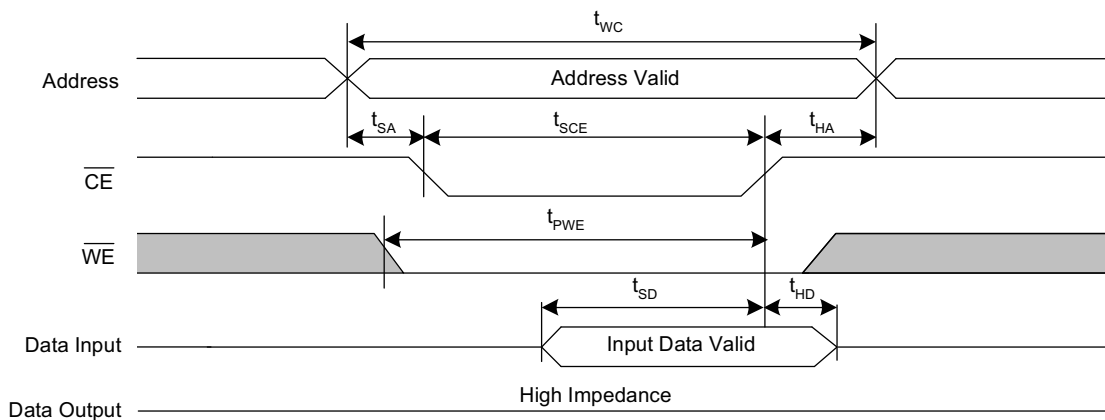


Figure 8. SRAM Write Cycle #2 ($\overline{\text{CE}}$ Controlled) [22, 23, 24]



Notes

21. $\overline{\text{WE}}$ must be HIGH during SRAM read cycles.
22. HSB must remain HIGH during READ and WRITE cycles.
23. If $\overline{\text{WE}}$ is low when $\overline{\text{CE}}$ goes low, the outputs remain in the high impedance state.
24. $\overline{\text{CE}}$ or $\overline{\text{WE}}$ must be $\geq V_{IH}$ during address transitions.

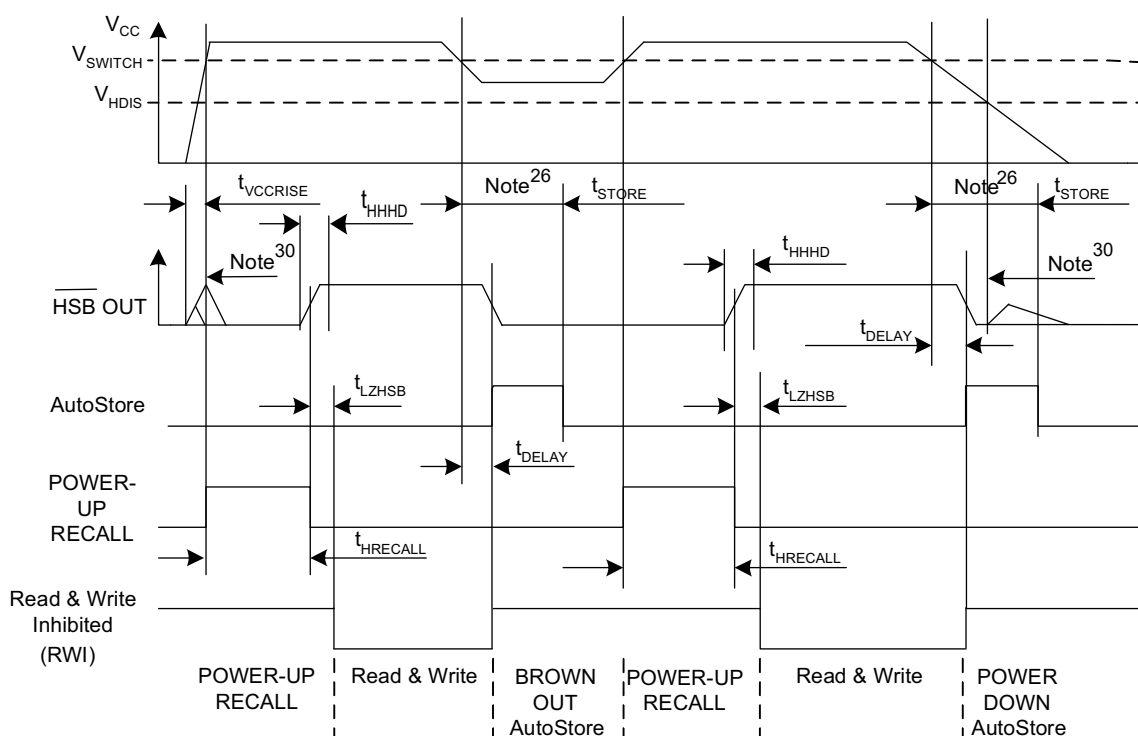
AutoStore/Power-Up RECALL

Over the [Operating Range](#)

| Parameters | Description | CY14B256LA | | Unit |
|-----------------------|---|------------|------|---------|
| | | Min | Max | |
| $t_{HRECALL}^{[25]}$ | Power-up RECALL duration | – | 20 | ms |
| $t_{STORE}^{[26]}$ | STORE cycle duration | – | 8 | ms |
| $t_{DELAY}^{[27]}$ | Time allowed to complete SRAM write cycle | – | 25 | ns |
| V_{SWITCH} | Low voltage trigger level | – | 2.65 | V |
| $t_{VCCRRISE}^{[28]}$ | V_{CC} rise time | 150 | – | μ s |
| $V_{HDIS}^{[28]}$ | HSB output disable voltage | – | 1.9 | V |
| $t_{LZHSB}^{[28]}$ | HSB to output active time | – | 5 | μ s |
| $t_{HHHD}^{[28]}$ | HSB high active time | – | 500 | ns |

Switching Waveforms

Figure 9. AutoStore or Power-Up RECALL ^[29]



Notes

25. $t_{HRECALL}$ starts from the time V_{CC} rises above V_{SWITCH} .
26. If an SRAM write has not taken place since the last nonvolatile cycle, no AutoStore or Hardware STORE takes place.
27. On a Hardware Store and AutoStore initiation, SRAM write operation continues to be enabled for time t_{DELAY} .
28. These parameters are guaranteed by design and are not tested.
29. Read and Write cycles are ignored during STORE, RECALL, and while V_{CC} is below V_{SWITCH} .
30. During power-up and power-down, HSB glitches when HSB pin is pulled up through an external resistor.

Software Controlled STORE/RECALL Cycle

Over the [Operating Range](#)

| Parameters [31, 32] | Description | 25 ns | | 45 ns | | Unit |
|---------------------|------------------------------------|-------|-----|-------|-----|---------|
| | | Min | Max | Min | Max | |
| t_{RC} | STORE/RECALL initiation cycle time | 25 | – | 45 | – | ns |
| t_{SA} | Address setup time | 0 | – | 0 | – | ns |
| t_{CW} | Clock pulse width | 20 | – | 30 | – | ns |
| t_{HA} | Address hold time | 0 | – | 0 | – | ns |
| t_{RECALL} | RECALL duration | – | 200 | – | 200 | μ s |

Switching Waveforms

Figure 10. \overline{CE} and \overline{OE} Controlled Software STORE/RECALL Cycle [32]

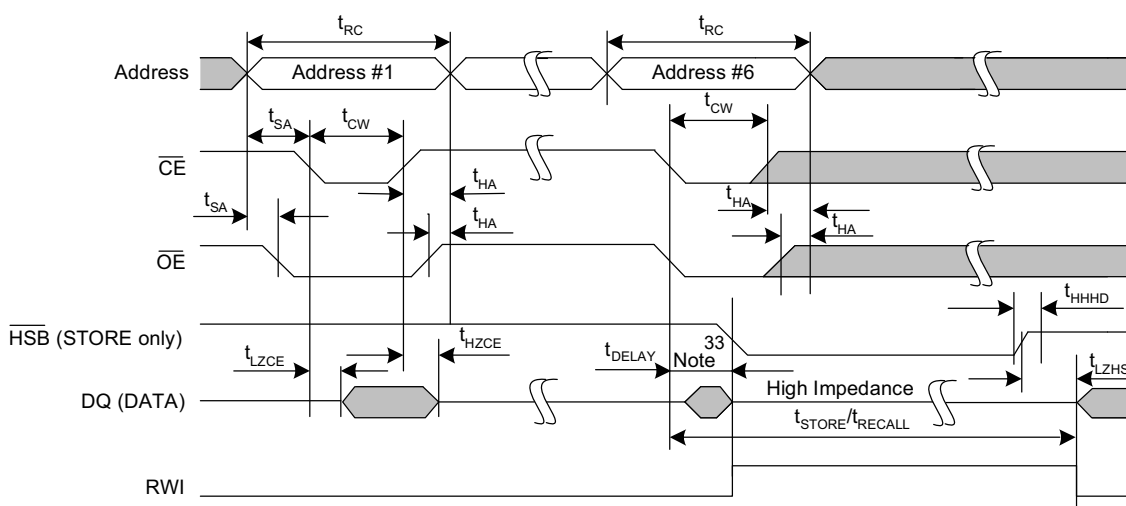
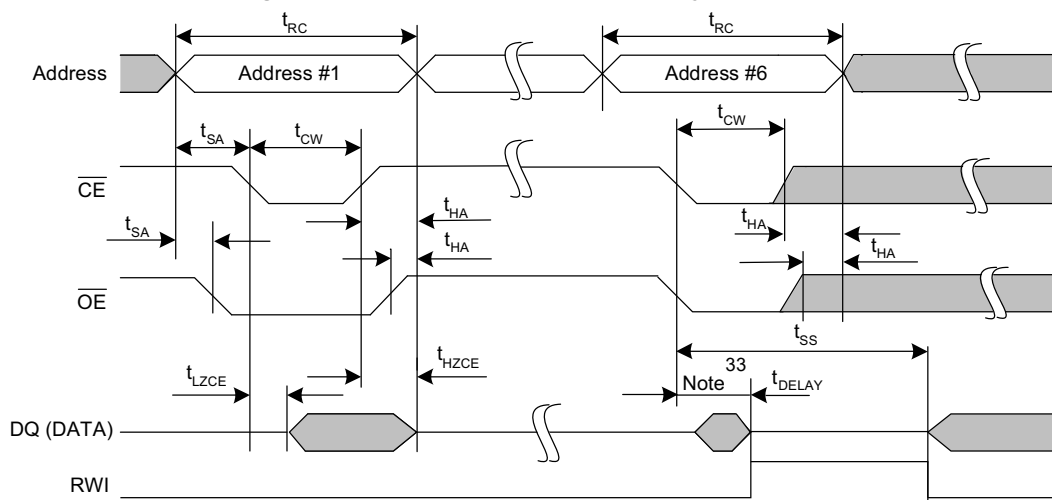


Figure 11. Autostore Enable / Disable Cycle [32]



Notes

31. The software sequence is clocked with \overline{CE} controlled or \overline{OE} controlled reads.

32. The six consecutive addresses must be read in the order listed in [Table 1 on page 6](#). \overline{WE} must be HIGH during all six consecutive cycles.

33. DQ output data at the sixth read may be invalid since the output is disabled at t_{DELAY} time.

Hardware STORE Cycle

Over the [Operating Range](#)

| Parameters | Description | CY14B256LA | | Unit |
|-------------------|---|------------|-----|---------|
| | | Min | Max | |
| t_{DHSB} | HSB to output active time when write latch is not set | – | 25 | ns |
| t_{PHSB} | Hardware STORE pulse width | 15 | – | ns |
| t_{SS} [34, 35] | Soft sequence processing time | – | 100 | μ s |

Switching Waveforms

Figure 12. Hardware STORE Cycle [36]

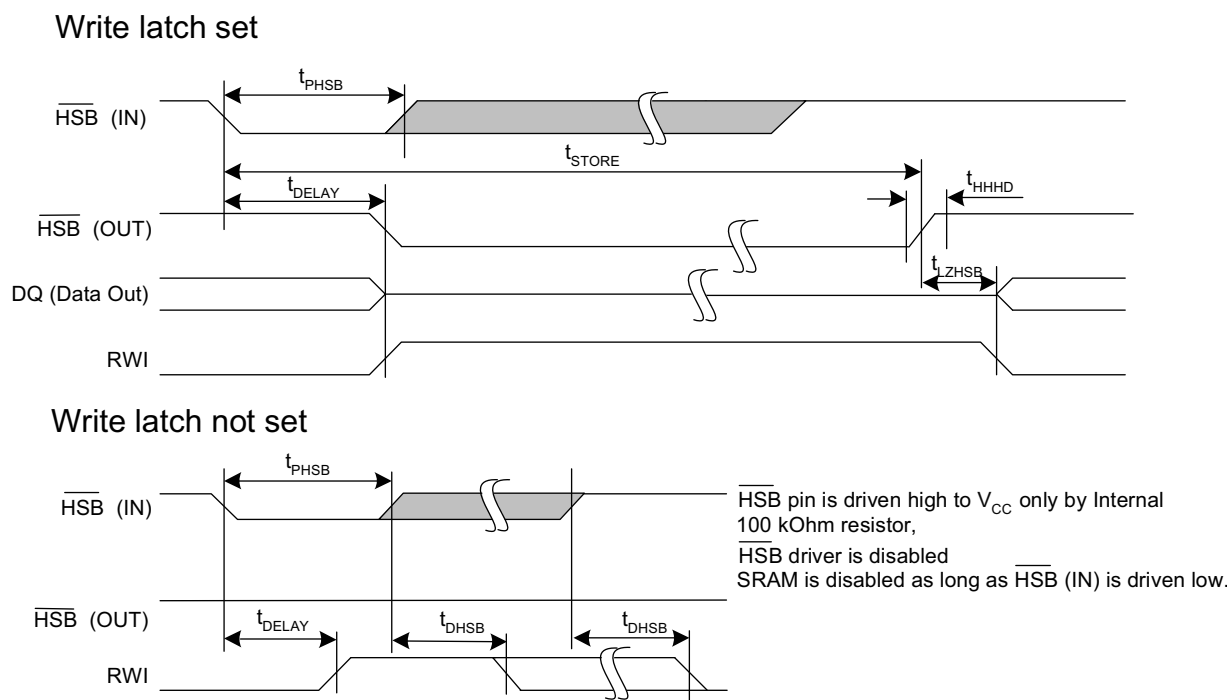
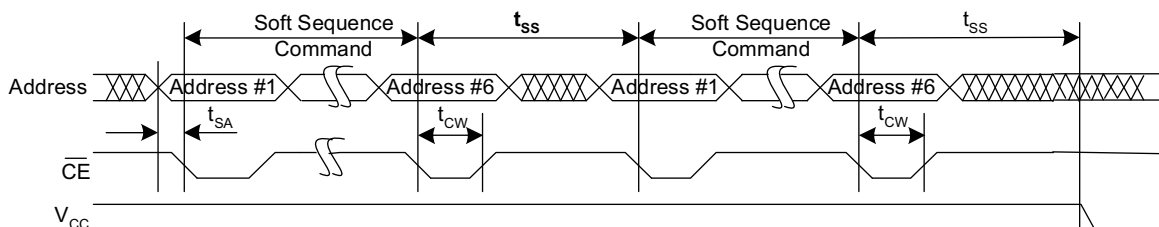


Figure 13. Soft Sequence Processing [34, 35]



Notes

34. This is the amount of time it takes to take action on a soft sequence command. V_{CC} power must remain HIGH to effectively register command.
 35. Commands such as STORE and RECALL lock out I/O until operation is complete which further increases this time. See the specific command.
 36. If an SRAM write has not taken place since the last nonvolatile cycle, no AutoStore or Hardware STORE takes place.

Truth Table For SRAM Operations

$\overline{\text{HSB}}$ must remain HIGH for SRAM operations.

Table 2. Truth Table

| CE | WE | OE | Inputs/Outputs | Mode | Power |
|----|----|----|---|---------------------|---------|
| H | X | X | High Z | Deselect/power-down | Standby |
| L | H | L | Data out (DQ ₀ –DQ ₇); | Read | Active |
| L | H | H | High Z | Output disabled | Active |
| L | L | X | Data in (DQ ₀ –DQ ₇); | Write | Active |

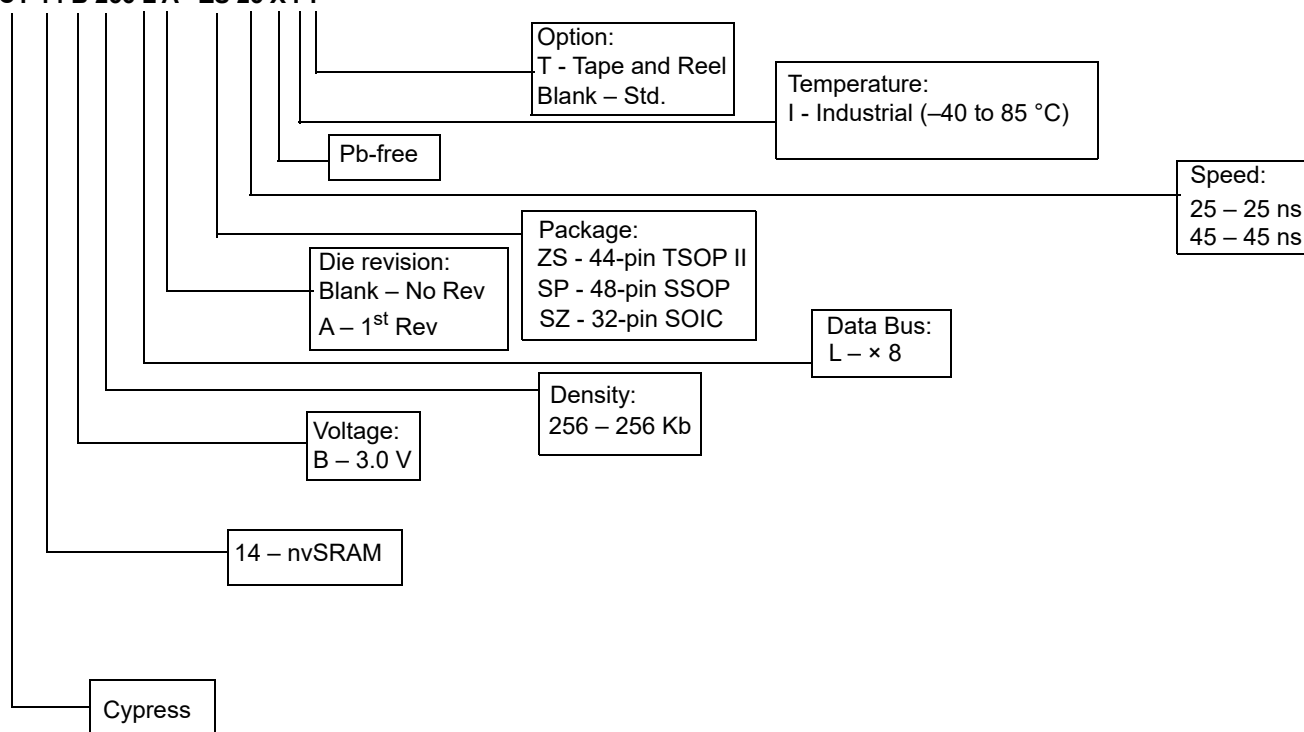
Ordering Information

| Speed (ns) | Ordering Code | Package Diagram | Package Type | Operating Range |
|------------|--------------------|-----------------|----------------|-----------------|
| 25 | CY14B256LA-ZS25XIT | 51-85087 | 44-pin TSOP II | Industrial |
| | CY14B256LA-ZS25XI | 51-85087 | 44-pin TSOP II | |
| | CY14B256LA-SP25XIT | 51-85061 | 48-pin SSOP | |
| | CY14B256LA-SP25XI | 51-85061 | 48-pin SSOP | |
| | CY14B256LA-SZ25XIT | 51-85127 | 32-pin SOIC | |
| | CY14B256LA-SZ25XI | 51-85127 | 32-pin SOIC | |
| 45 | CY14B256LA-SP45XIT | 51-85061 | 48-pin SSOP | |
| | CY14B256LA-SP45XI | 51-85061 | 48-pin SSOP | |
| | CY14B256LA-SZ45XIT | 51-85127 | 32-pin SOIC | |
| | CY14B256LA-SZ45XI | 51-85127 | 32-pin SOIC | |

All the above parts are Pb-free.

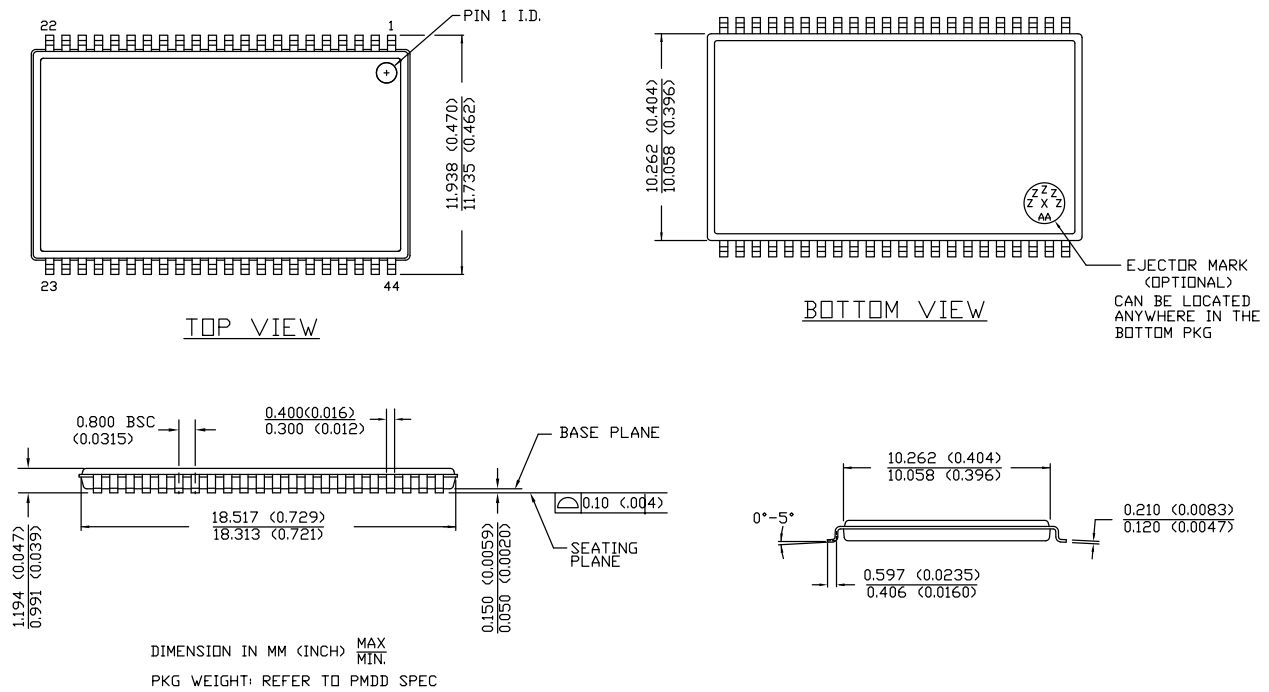
Ordering Code Definitions

CY 14 B 256 L A - ZS 25 X I T



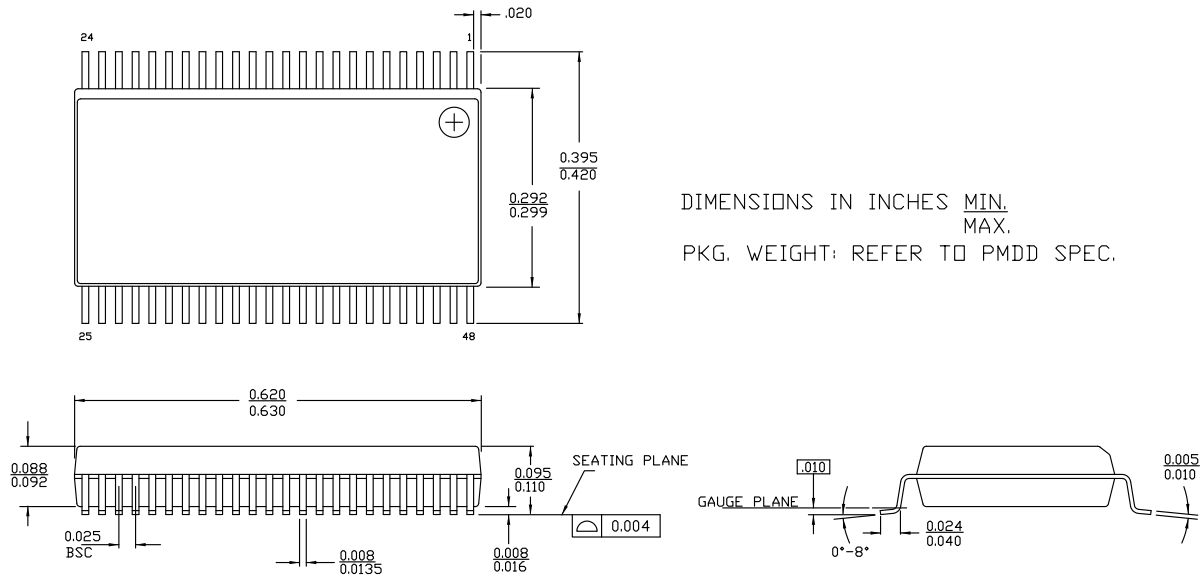
Package Diagrams

Figure 14. 44-pin TSOP II Package Outline, 51-85087



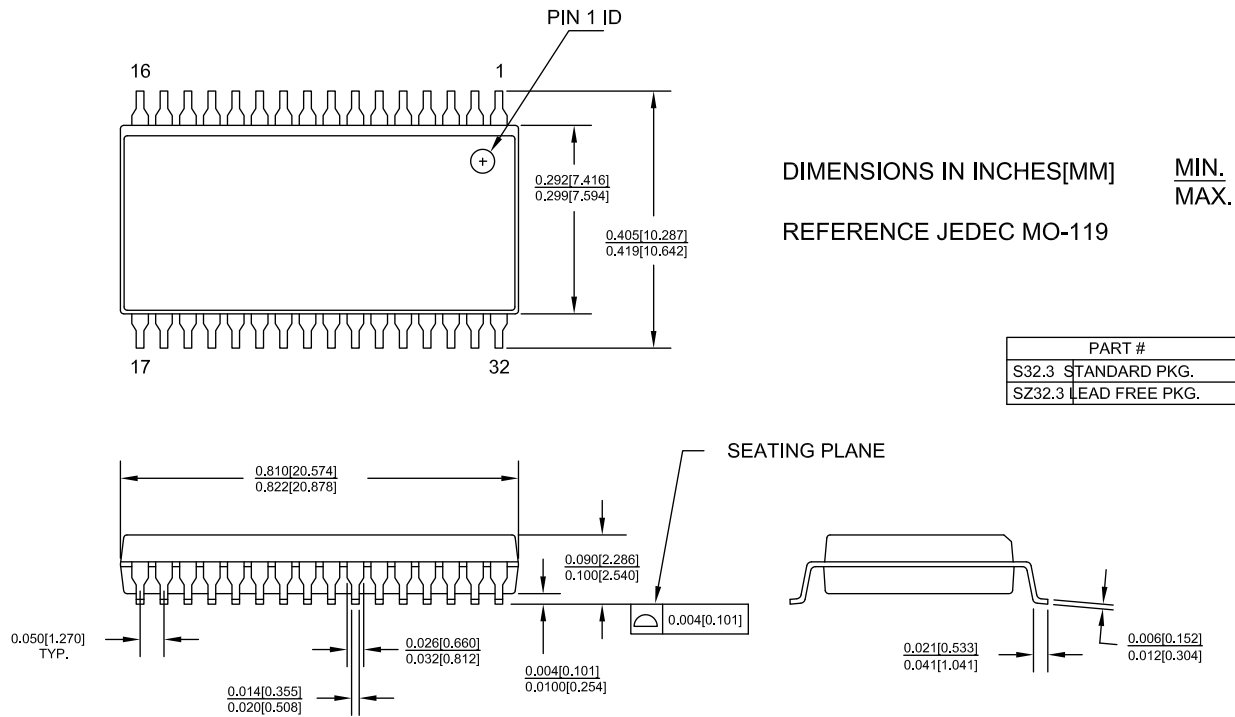
51-85087 *E

Package Diagrams (continued)

Figure 15. 48-pin SSOP (300 Mils) Package Outline, 51-85061


51-85061 *F

Package Diagrams (continued)

Figure 16. 32-pin SOIC (300 Mil) Package Outline, 51-85127


51-85127 *D

Acronyms

| Acronym | Description |
|---------|--|
| CE | chip enable |
| CMOS | complementary metal oxide semiconductor |
| EIA | electronic industries alliance |
| HSB | hardware store busy |
| I/O | input/output |
| nvSRAM | non-volatile static random access memory |
| OE | output enable |
| RoHS | restriction of hazardous substances |
| RWI | read and write inhibited |
| SRAM | static random access memory |
| SSOP | shrink small outline package |
| SOIC | small outline integrated circuit |
| TSOP | thin small outline package |
| WE | write enable |

Document Conventions

Units of Measure

| Symbol | Unit of Measure |
|--------|-----------------|
| °C | degree Celsius |
| kΩ | kilohm |
| MHz | megahertz |
| μA | microampere |
| μF | microfarad |
| μs | microsecond |
| mA | milliampere |
| ms | millisecond |
| ns | nanosecond |
| Ω | ohm |
| % | percent |
| pF | picofarad |
| V | volt |
| W | watt |

Document History Page

| Document Title: CY14B256LA, 256-Kbit (32 K × 8) nvSRAM Document Number: 001-54707 | | | |
|--|---------|-----------------|---|
| Revision | ECN | Submission Date | Description of Change |
| ** | 2746918 | 07/31/2009 | New data sheet. |
| *A | 2772059 | 09/30/2009 | Updated Software STORE, RECALL and Autostore Enable, Disable soft sequence |
| *B | 2829117 | 12/16/09 | Updated STORE cycles to QuantumTrap from 200K to 1 Million Updated 48-pin SSOP package diagram Added Contents . Moved to external web |
| *C | 2894560 | 03/18/10 | Added more clarity on HSB pin operation Updated HSB pin operation in Figure 9 and updated footnote 21 Removed from ordering information table. CY14B256LA-ZS25XIT, CY14B256LA-ZS25XI, CY14B256LA-ZS45XIT, CY14B256LA-ZS45XI Updated Package Diagrams for spec 51-85061 and 51-85087. Updated copyright section. Updated links under section sales, solutions, and legal information. |
| *D | 2995066 | 07/28/2010 | Added CY14B256LA-ZS25XI part to ordering information table. |
| *E | 3074570 | 10/29/10 | Added CY14B256LA-ZS25XIT part to ordering information table. Added Units of Measure table |
| *F | 3143330 | 01/17/2011 | Fixed typo in Figure 9 . |
| *G | 3315247 | 07/15/2011 | Updated DC Electrical Characteristics (Added Note 11 and referred the same note in V_{CAP} parameter). Updated Capacitance (Included Input capacitance (for \overline{HSB}) and Output capacitance (for HSB)). Updated Thermal Resistance (Θ_{JA} and Θ_{JC} values for 44-pin TSOP II packages). Updated AC Switching Characteristics (Added Note 14 and referred the same note in Parameters). |
| *H | 3430452 | 11/04/2011 | Corrected alignment of footnote 24 . Updated Package Diagrams . |
| *I | 3660776 | 06/29/2012 | Updated DC Electrical Characteristics (Added V_{VCAP} parameter and its details, added Note 12 and referred the same note in V_{VCAP} parameter, also referred Note 13 in V_{VCAP} parameter). |
| *J | 3759425 | 09/28/2012 | Updated Maximum Ratings (Removed "Ambient temperature with power applied" and included "Maximum junction temperature"). Updated Package Diagrams (spec 51-85087 (Changed revision from *D to *E), spec 51-85061 (Changed revision from *E to *F)). |
| *K | 4568935 | 11/14/2014 | Added documentation related hyperlink in page 1 |
| *L | 6868237 | 04/25/2020 | Updated to template. Updated Spec 51-85127 *C to *D in Package Diagrams . |

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